

## LAMP2006 Session Chart

Day-1: May 16, 2006, Tuesday		Day-2: May 17, 2006, Wednesday						
AM	<b>N/A</b>	Room 1 (Science Hall) East Dist. #1 Bldg., 4F	Room 2 (AV Room) East Dist. #1Bldg., 4F	Room 3 East Dist. #1 Bldg., 4F	Room 4 West Dist. #4 Bldg., 2F			
		<b>SP L2-1</b> Fundamental Issues in Laser Direct- Write (9:00-10:30) (p.36)	<b>LPM-05</b> Ultrafast Laser Processing - Theory & Dynamics - (9:00-10:30) (p.36)	<b>LPM-09</b> Nanomaterials Synthesis (9:00-10:30) (p.37)	<b>HPL-04</b> Welding 1 (9:00-10:30) (p.37)			
	<b>COFFEE BREAK</b>							
<b>Opening Remarks</b> (10:00-10:10)		<b>SP L2-2</b> Laser Direct- Write of Optical Materials (10:40-12:10) (p.36)	<b>LPM-06</b> Ultrafast Laser Processing - Fundamentals (10:50-12:10) (p.36)	<b>LPM-10</b> Nanomaterials Treatment (10:50-12:10) (p.37)	<b>HPL-05</b> Welding 2 (10:45-12:15) (p.37)			
<b>Plenary Talks</b> (10:10-12:10) Room 1(Science Hall), East Dist., #1 Bldg., 4F (p.29)								
<b>LUNCH TIME</b> (Complimentary Sandwiches, Riceball, Juice & Green Tea will be served at Atrium, East Dist. 1F, First-come, First-Served basis)								
PM	Room 1 (Science Hall) East Dist. #1 Bldg., 4F	Room 2 (AV Room) East Dist. #1Bldg., 4F	Room 3 East Dist. #1 Bldg., 4F	Room 4 West Dist. #4 Bldg., 2F	<b>SP L2-3</b> Laser Direct- Write Applications (13:10-15:00) (p.38)	<b>LPM-07</b> Ultrafast Laser Processing - Ablation - (13:40-15:00) (p.38)	<b>LPM-11</b> Microdrilling & Cutting (13:50-14:50) (p.39)	<b>HPL-06</b> Welding 3 (13:30-15:00) (p.39)
	<b>SP L1-1</b> High Repetition Ultrafast Laser Processing (13:20-14:50)	<b>LPM-01</b> Nano- technology (13:30-15:00) (p.30)	<b>LPM-03</b> Laser Crystallization (13:30-14:50) (p.31)	<b>HPL-01</b> Analysis of Process Phenomenon (13:30-14:40) (p.31)	<b>COFFEE BREAK</b>			
	<b>SP L1-2</b> Ultrafast Laser Processing Applications (15:10-16:50) (p.30)	<b>LPM-02</b> Nano- fabrication (15:20-16:40) (p.30)	<b>LPM-04</b> Surface Treatment & Modification (15:20-16:40) (p.31)	<b>HPL-02</b> Monitoring and Process Control (15:20-16:40) (p.31)	<b>LPM-12</b> Micro- machining (15:10-16:50) (p.38)	<b>LPM-08</b> Ultrafast Laser Processing - Nano- structuring (15:20-16:40) (p.38)	<b>HPL-03</b> Material Removal (15:20-16:40) (p.39)	<b>HPL-07</b> Welding 4 (15:20-16:20) (p.39)
	<b>Poster Session 1 Short Presentations</b> (17:00-18:00) (p.30-31)		<b>Poster Session 2 Short Presentations</b> (17:00-18:00) (p.38-39)					
	<b>Poster Session 1 &amp; Table-Top Exhibitions</b> (18:00 ~ 19:30) Atrium, East Dist., 1F Snack & Beer Served (p.32-35)		<b>Poster Session 2 &amp; Table-Top Exhibitions</b> (18:00 ~ 19:30) Atrium, East Dist., 1F Snack & Beer Served (p.40-43)					
	<b>COFFEE BREAK</b>							
	<b>Banquet</b> Atrium, East Dist., 1F (18:30-21:00) (p.13, 48-49)							

## LAMP2006 Session Chart

Day-3: May 18, 2006, Thursday				Day-4: May 19, 2006, Friday			
Room 1 (Science Hall) East Dist. #1 Bldg., 4F	Room 2 (AV Room) East Dist. #1Bldg., 4F	Room 3 East Dist. #1 Bldg., 4F	Room 4 West Dist. #4 Bldg., 2F	Room 1 (Science Hall) East Dist. #1 Bldg., 4F	Room 2 (AV Room) East Dist. #1Bldg., 4F	Room 3 East Dist. #1 Bldg., 4F	Room 4 West Dist. #4 Bldg., 2F
<b>SP J1-1</b> Potential of High-Power Fiber and Disk Lasers (9:00-10:30) (p.44)	<b>LPM-13</b> Ultrafast Laser Processing - Micromachining (9:00-10:20) (p.44)	<b>LPM-18</b> Fundamentals & Process Monitoring (9:00-10:20) (p.45)	<b>HPL-10</b> Surface Treatment 1 (9:00-10:20) (p.45)	<b>SP L3-1</b> Laser Processing for Biomedical Applications 1 (9:00-10:30) (p.50)	<b>LPM-23</b> Micro- processing for Semi- conductor Industry (9:00-10:30) (p.50)	<b>LPM-26</b> Film Deposition (9:00-10:30) (p.51)	<b>HPL-15</b> Hybrid Welding 1 (9:00-10:10) (p.51)
<b>COFFEE BREAK</b>							
<b>SP J1-2</b> High-Power Applications of Fiber and Disk Lasers (10:40-12:40) (p.44)	<b>LPM-14</b> Ultrafast Laser Processing - Glass Processing (10:40-12:10) (p.44)	<b>LPM-19</b> Organic Materials Micro- processing (10:40-12:10) (p.45)	<b>HPL-11</b> Surface Treatment 2 (10:40-11:40) (p.45)	<b>SP L3-2</b> Laser Processing for Biomedical Applications 2 (10:50-12:20) (p.50)	<b>LPM-24</b> Micro- processing for Electronics Industry I (10:50-12:20) (p.50)	<b>LPM-27</b> Optics & Systems (10:50-12:10) (p.51)	<b>HPL-16</b> Hybrid Welding 2 (10:50-12:10) (p.51)
<b>LUNCH TIME</b>							
<b>SP J1-3</b> Micro- fabrication by Fiber and Disk Lasers (13:30-15:00) (p.46)	<b>LPM-15</b> Manufacture of Microdevices & Components (13:30-15:00) (p.46)	<b>LPM-20</b> Laser & Photo- chemistry (13:30-15:00) (p.47)	<b>HPL-12</b> Surface Treatment 3 - Laser Cladding and Prototyping (13:30-15:00) (p.47)	<b>SP L3-3</b> Laser Processing for Biomedical Applications 3 (13:30-15:00) (p.52)	<b>LPM-25</b> Micro- processing for Electronics Industry II (13:30-15:00) (p.52)	<b>LPM-28</b> Laser Devices & Light Source (13:40-15:00) (p.53)	<b>HPL-17</b> Plastic Joining (13:40-15:00) (p.53)
<b>COFFEE BREAK</b>				<b>COFFEE BREAK</b>			
<b>HPL-08</b> Latest Novel Processing (15:20-16:50) (p.46)	<b>LPM-16</b> 3D Micro & Nanofabrication (15:40-16:40) (p.46)	<b>LPM-21</b> Liquid- Assisted Ablation (15:20-16:40) (p.47)	<b>HPL-13</b> Surface Treatment 4 (15:20-16:40) (p.47)	<b>Joint Session</b> Crossover Regions of LPM and HPL (15:20-16:40) Room 1 (Science Hall), East Dist., #1Bldg., 4F (p.54)			
<b>COFFEE BREAK</b>				<b>Outstanding Student Poster Paper Awards Closing Remarks</b> (p.54)			
<b>HPL-09</b> Laser System (17:00-18:20) (p.48)	<b>LPM-17</b> 3D Micro & Nanolithography (17:00-18:20) (p.48)	<b>LPM-22</b> Manufacture of Photonic Devices (17:00-18:20) (p.49)	<b>HPL-14</b> Inovations (17:00-18:20) (p.49)				
<b>Banquet</b> Atrium, East Dist., 1F (18:30-21:00) (p.13, 48-49)							